

- Compliant with IEEE 802.3 standards
- Low profile surface mount package, open construction
- Operating Temperature: -40°C to +85°C
- Storage Temperature: -55°C to +125°C
- Moisture Sensitivity Level: 1
- Terminal Finish: Sn63Pb37

Electrical Specifications @ 25°C

Part Number	Insertion Loss (dB MAX)					Return Loss (dB MIN)						Crosstalk (dB MIN)			DM to CM Rejection Ratio (dB MIN)			DWV (Vrms)
	0.10 MHz	1 MHz	300 MHz	400 MHz	500 MHz	1 MHz	10 MHz	100 MHz	300 MHz	400 MHz	500 MHz	1 MHz	100 MHz	400 MHz	1 MHz	250 MHz	500 MHz	
10GB-6007	3.0	1.2	1.2	2.4	2.4	22	24	20	13	10	7	40	37	30	40	30	22	1500

NOTES:

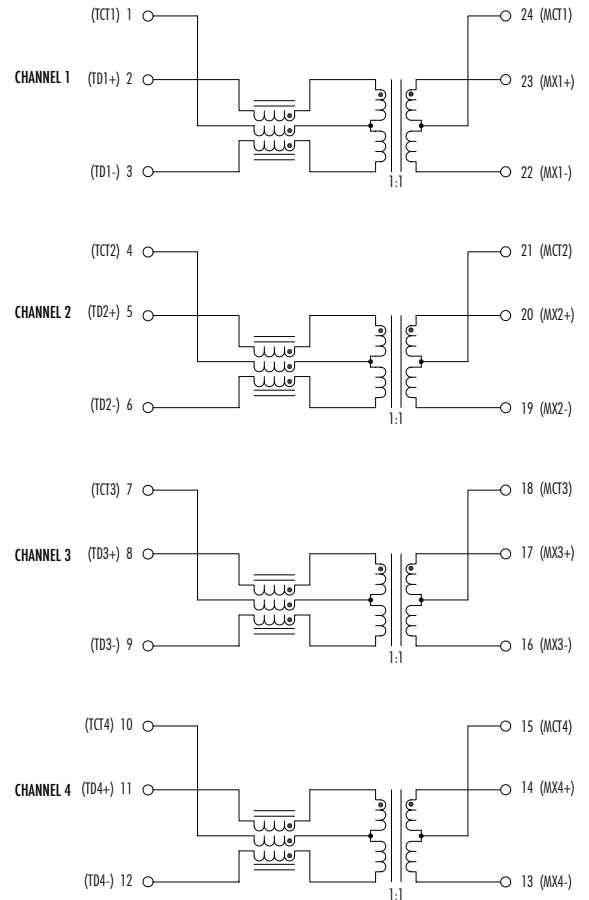
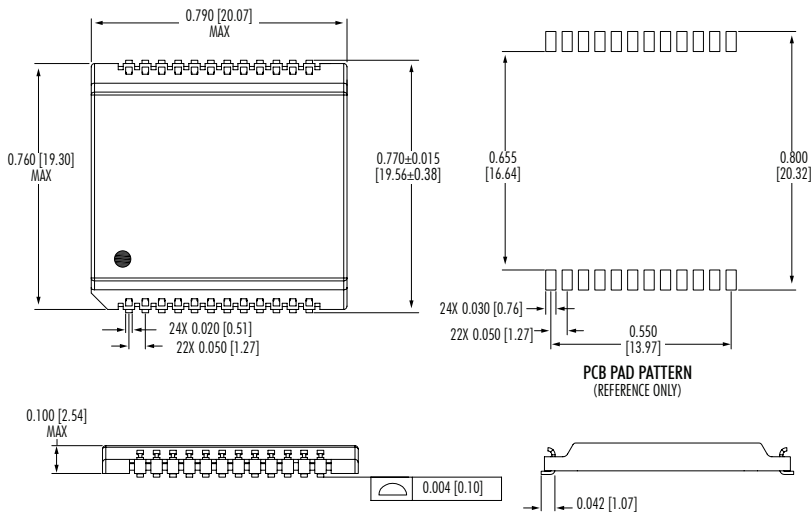
- Add suffix "NL" for RoHS compliant version; i.e. 10GB-6007 becomes 10GB-6007NL.
- For Tape & Reel packaging, add "T" suffix at the end of the part number: i.e. 10GB-6007NLT

Mechanicals

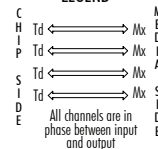
Electrical Schematics

10GB-6007

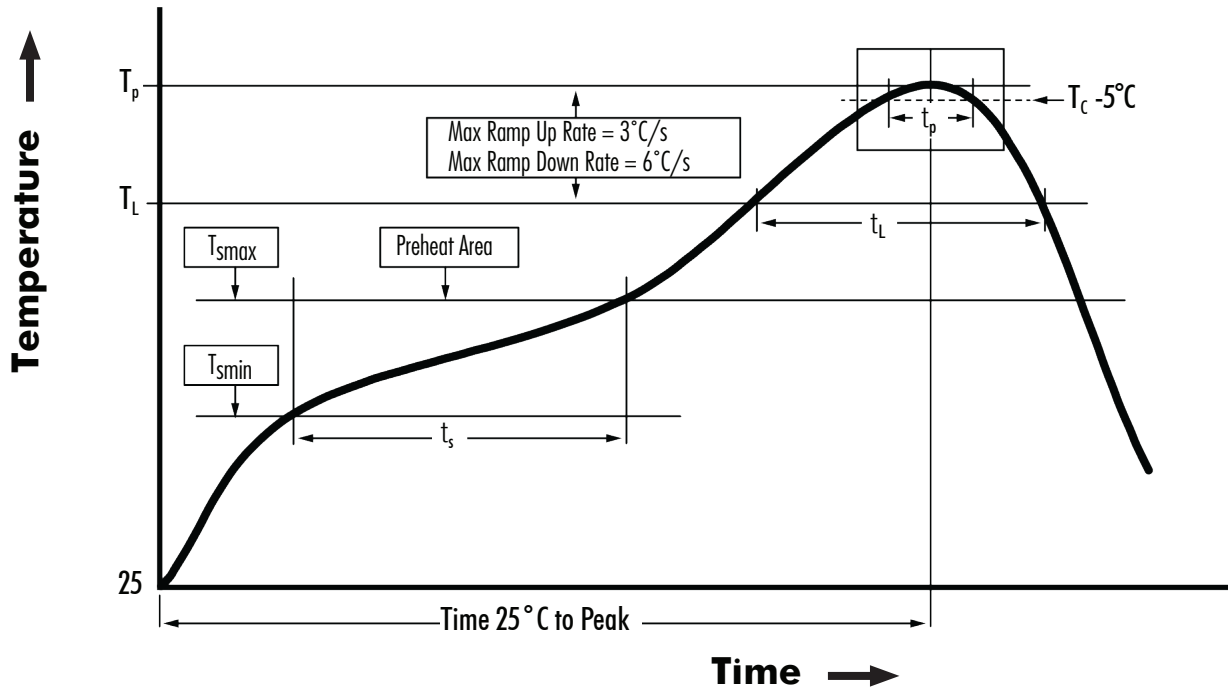
Dimensions: inch [mm]
Tolerance (unless otherwise specified): ±0.010 [0.25]



LEGEND



Tin/Lead Recommended Reflow Profile (Based on J-STD-020D)



$T_{S_{MIN}}$ (°C)	$T_{S_{MAX}}$ (°C)	T_L (°C)	T_P (°C MAX)	t_s (s)	t_L (s)	t_p (s MAX)	Ramp-up rate (T_L to T_P)	Ramp-down rate (T_P to T_L)	Time 25°C to peak temperature (s MAX)
100	150	183	220	60 - 120	60 - 150	20	3°C/s MAX	6°C/s MAX	360

NOTES:

1. All temperatures measured on the package leads.
2. Maximum number of reflow cycles not to exceed 2.

